

## 1. General description

Silicon Carbide Schottky diode in a SMB plastic package, designed for high frequency switched-mode power supplies.



## 2. Features and benefits

- Highly stable switching performance
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

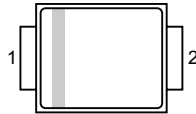

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V <sub>RRM</sub>	repetitive peak reverse voltage		650				V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse; T <sub>lead</sub> ≤ 43 °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	3				A
T <sub>j</sub>	junction temperature		175				°C
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 3 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>		-	1.5	1.7	V
		I <sub>F</sub> = 3 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 5</a>		-	1.72	2	V
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 3 A; dI <sub>F</sub> /dt = 500 A/μs; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	10	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D03650MB	SMB	WNSC2D03650MBJ	Reel	3000	SMB	20-Feb-2017

## 7. Marking

Table 4. Marking codes

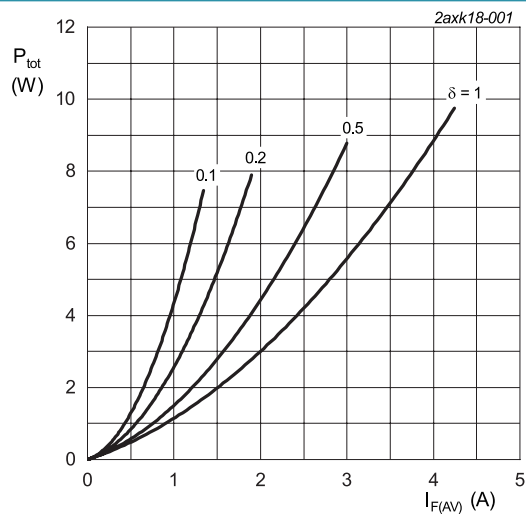
Type number	Marking codes
WNSC2D03650MB	2365ES

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

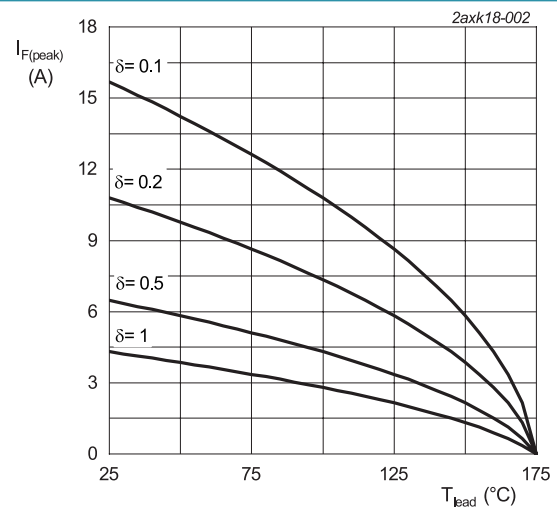
Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{RWM}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{lead} \leq 43^\circ\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	3	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{lead} \leq 43^\circ\text{C}$ ; square-wave pulse	6	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\ \text{ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse	18	A
		$t_p = 10\ \mu\text{s}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; square-wave pulse	235	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 10\ \text{ms}$	1.62	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.789\ \text{V}; R_s = 0.3560\ \Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Current derating as a function of lead temperature**

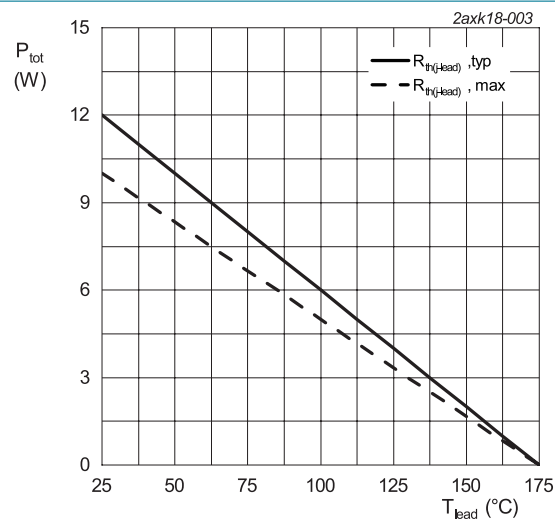


Fig. 3. Total power dissipation as a function of lead temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	<a href="#">Fig. 4</a>		-	12.5	15	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	90	-	K/W

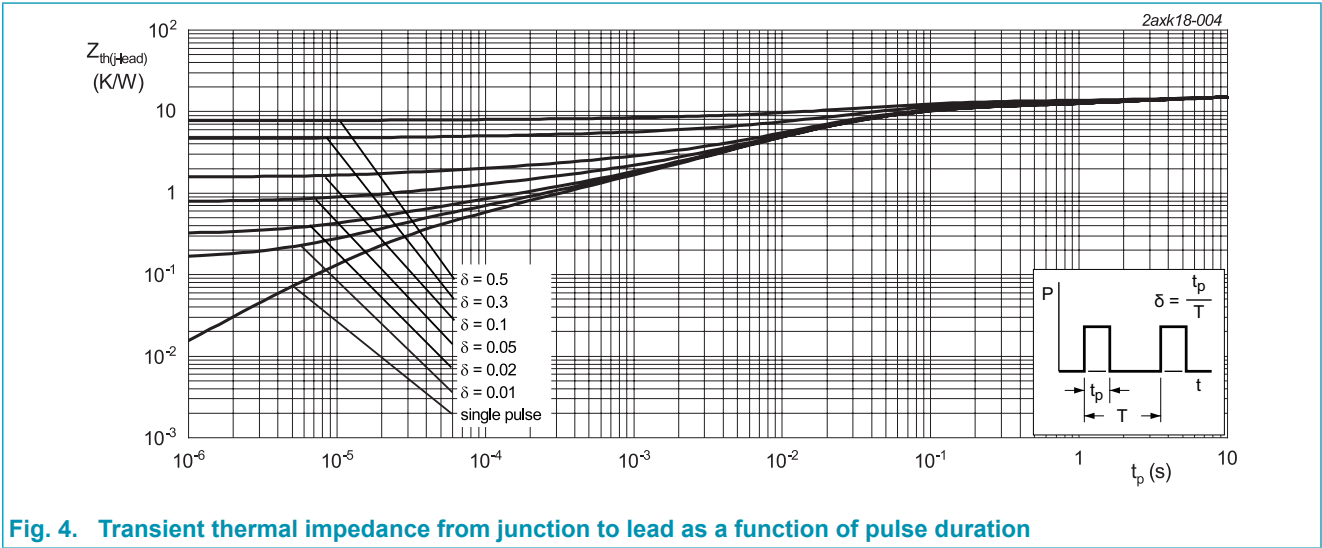
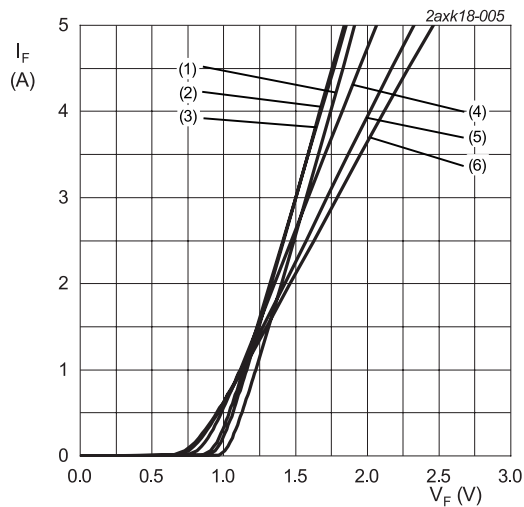


Fig. 4. Transient thermal impedance from junction to lead as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward current	I <sub>F</sub> = 3 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>		-	1.5	1.7	V
		I <sub>F</sub> = 3 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 5</a>		-	1.72	2	V
		I <sub>F</sub> = 3 A; T <sub>j</sub> = 175 °C; <a href="#">Fig. 5</a>		-	1.8	2.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	0.2	20	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <a href="#">Fig. 6</a>		-	10	200	μA
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 3 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	10	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	130	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	17	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	15	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 2.7 A; L = 5 mH; T <sub>j</sub> (init) = 25 °C		18	-	-	mJ



$V_o = 0.789\text{ V}; R_s = 0.3560\text{ }\Omega$

- (1)  $T_J = -55\text{ }^\circ\text{C}$ ; typical values
- (2)  $T_J = 0\text{ }^\circ\text{C}$ ; typical values
- (3)  $T_J = 25\text{ }^\circ\text{C}$ ; typical values
- (4)  $T_J = 100\text{ }^\circ\text{C}$ ; typical values
- (5)  $T_J = 150\text{ }^\circ\text{C}$ ; typical values
- (6)  $T_J = 175\text{ }^\circ\text{C}$ ; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

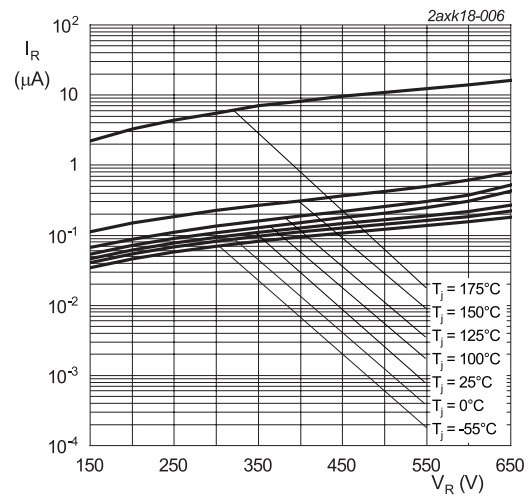


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

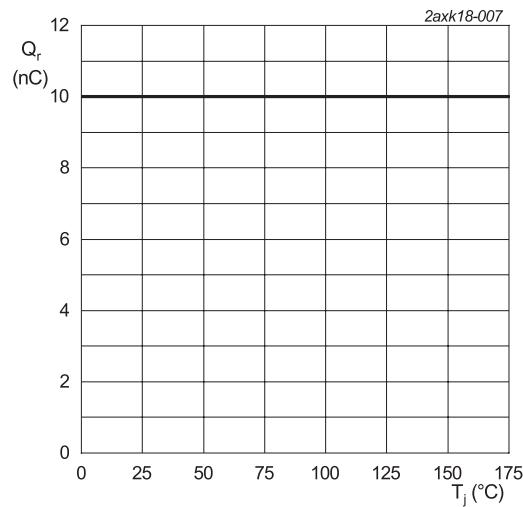
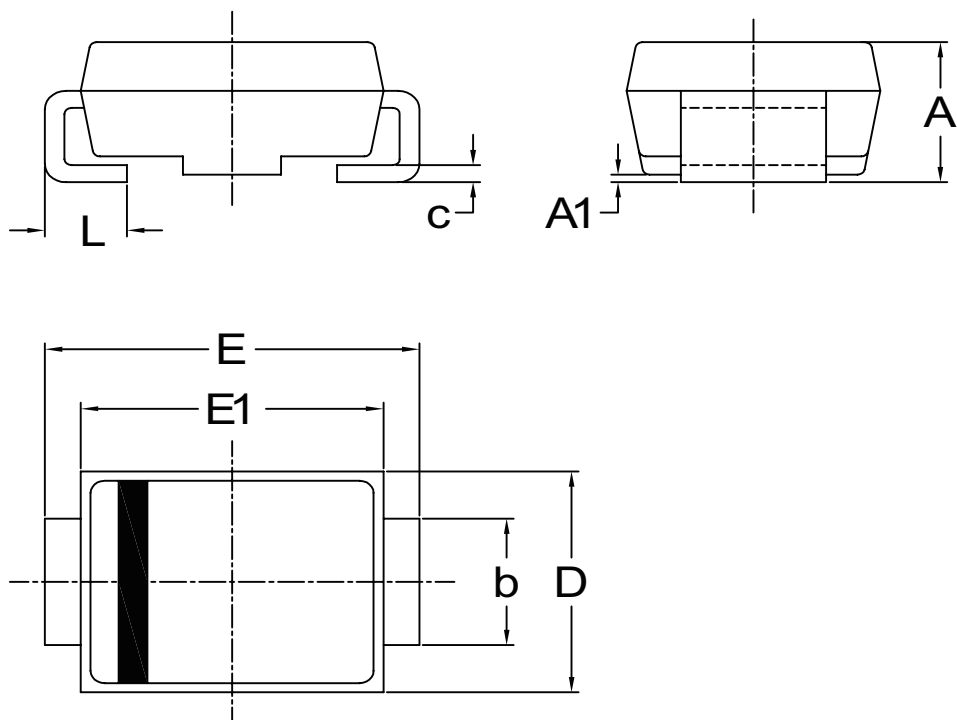


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline



UNIT	A	A1	b	c	D	E	E1	L	
mm	Max	2.50	0.20	2.21	0.31	3.95	5.60	4.60	1.60
	Min	2.00	0.05	1.96	0.15	3.30	5.20	4.05	0.75

Remark: Dimensions D and E1 do not include mold flash.



## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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